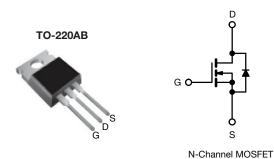


## **Power MOSFET**



PRODUCT SUMMARY					
V <sub>DS</sub> (V)	50	500			
$R_{DS(on)}(\Omega)$	V <sub>GS</sub> = 10 V	0.85			
Q <sub>g</sub> max. (nC)	6	3			
Q <sub>gs</sub> (nC)	9	.3			
Q <sub>gd</sub> (nC)	3	32			
Configuration	Sin	Single			

#### **FEATURES**

- Dynamic dV/dt rating
- Repetitive avalanche rated
- · Fast switching
- · Ease of paralleling
- Simple drive requirements
- Material categorization: for definitions of compliance please see <a href="https://www.vishay.com/doc?99912">www.vishay.com/doc?99912</a>

#### Note

\* This datasheet provides information about parts that are RoHS-compliant and / or parts that are non RoHS-compliant. For example, parts with lead (Pb) terminations are not RoHS-compliant. Please see the information / tables in this datasheet for details

#### **DESCRIPTION**

Third generation power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-220AB package is universally preferred for all commercial-industrial applications at power dissipation levels to approximately 50 W. The low thermal resistance and low package cost of the TO-220AB contribute to its wide acceptance throughout the industry.

ORDERING INFORMATION	
Package	TO-220AB
Lead (Pb)-free	IRF840PbF
Lead (Pb)-free and halogen-free	IRF840PbF-BE3

<b>ABSOLUTE MAXIMUM RATINGS</b> (T <sub>C</sub> = 25 °C, unless otherwise PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-source voltage			V <sub>DS</sub>	500	V	
Gate-source voltage			$V_{GS}$	± 20	V	
Continuous drain current	V <sub>GS</sub> at 10 V	$T_{\rm C} = 25  ^{\circ}{\rm C}$ $T_{\rm C} = 100  ^{\circ}{\rm C}$	,	8.0	А	
		T <sub>C</sub> = 100 °C	I <sub>D</sub>	5.1		
Pulsed drain current <sup>a</sup>			I <sub>DM</sub>	32	1	
Linear derating factor				1.0	W/°C	
Single pulse avalanche energy b			E <sub>AS</sub>	510	mJ	
Repetitive avalanche current a			I <sub>AR</sub>	8.0	А	
Repetitive avalanche energy <sup>a</sup>			E <sub>AR</sub>	13	mJ	
Maximum power dissipation	T <sub>C</sub> =	25 °C	P <sub>D</sub>	125	W	
Peak diode recovery dV/dt <sup>c</sup>			dV/dt	3.5	V/ns	
Operating junction and storage temperature range	ating junction and storage temperature range			-55 to +150	°C	
Soldering recommendations (peak temperature) <sup>d</sup>	For 10 s			300		
Mounting torque	6-32 or M3 screw			10	lbf · in	
				1.1	N⋅m	

### Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- b.  $V_{DD}$  = 50 V, starting  $T_J$  = 25 °C, L = 14 mH,  $R_g$  = 25  $\Omega$ ,  $I_{AS}$  = 8.0 A (see fig. 12)
- c.  $I_{SD} \le 8.0$  A,  $dI/dt \le 100$  A/ $\mu$ s,  $V_{DD} \le V_{DS}$ ,  $T_J \le 150$  °C
- d. 1.6 mm from case



# Vishay Siliconix

THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum junction-to-ambient	R <sub>thJA</sub>	-	62		
Case-to-sink, flat, greased surface	R <sub>thCS</sub>	0.50	-	°C/W	
Maximum junction-to-case (drain)	R <sub>thJC</sub>	-	1.0		

PARAMETER	SYMBOL	TEST	MIN.	TYP.	MAX.	UNIT	
Static							
Drain-source breakdown voltage	$V_{DS}$	$V_{GS} = 0$	500	-	-	V	
V <sub>DS</sub> temperature coefficient	$\Delta V_{DS}/T_{J}$	Reference t	-	0.78	-	V/°C	
Gate-source threshold voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$		2.0	-	4.0	V
Gate-source leakage	I <sub>GSS</sub>	V <sub>GS</sub> = ± 20 V		-	-	± 100	nA
Zana anto college admin account			00 V, V <sub>GS</sub> = 0 V	-	-	25	μА
Zero gate voltage drain current	I <sub>DSS</sub>	$V_{DS} = 400 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 125 \text{ °C}$		-	-	250	
Drain-source on-state resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 4.8 A <sup>b</sup>	-	-	0.85	Ω
Forward transconductance	9 <sub>fs</sub>	V <sub>DS</sub> = 50 V, I <sub>D</sub> = 4.8 A <sup>b</sup>		4.9	-	-	S
Dynamic							•
Input capacitance	C <sub>iss</sub>	$V_{GS} = 0 \text{ V},$ $V_{DS} = 25 \text{ V},$ $f = 1.0 \text{ MHz}, \text{ see fig. } 5$		-	1300	-	pF
Output capacitance	C <sub>oss</sub>			-	310	-	
Reverse transfer capacitance	C <sub>rss</sub>			-	120	-	
Total gate charge	Qg	$V_{GS} = 10 \text{ V}$ $I_{D} = 8 \text{ A}, V_{DS} = 400 \text{ V},$ see fig. 6 and 13 b		-	-	63	
Gate-source charge	$Q_{gs}$		-	-	9.3	nC	
Gate-drain charge	Q <sub>gd</sub>		-	-	32		
Turn-on delay time	t <sub>d(on)</sub>	$V_{DD}$ = 250 V, $I_{D}$ = 8 A $R_{g}$ = 9.1 $\Omega$ , $R_{D}$ = 31 $\Omega$ , see fig. 10 $^{b}$		-	14	-	ns
Rise time	t <sub>r</sub>			-	23	-	
Turn-off delay time	t <sub>d(off)</sub>			-	49	-	
Fall time	t <sub>f</sub>			-	20	-	
Internal drain inductance	L <sub>D</sub>	Between lead, 6 mm (0.25") from package and center of die contact		-	4.5	-	- nH
Internal source inductance	L <sub>S</sub>			-	7.5	-	
Gate input resistance	R <sub>g</sub>	f = 1 MHz, open drain		0.6	-	2.8	Ω
<b>Drain-Source Body Diode Characteristic</b>	cs						
Continuous source-drain diode current	I <sub>S</sub>	MOSFET symbol showing the integral reverse p - n junction diode		-	-	8.0	Α
Pulsed diode forward current <sup>a</sup>	I <sub>SM</sub>			-	-	32	
Body diode voltage	V <sub>SD</sub>	T <sub>J</sub> = 25 °C, I <sub>S</sub> = 8 A, V <sub>GS</sub> = 0 V b		-	-	2.0	V
Body diode reverse recovery time	t <sub>rr</sub>	T <sub>J</sub> = 25 °C, I <sub>F</sub> = 8 A, dl/dt = 100 A/μs b		-	460	970	ns
Body diode reverse recovery charge	Q <sub>rr</sub>			-	4.2	8.9	μC
Forward turn-on time	t <sub>on</sub>	Intrinsic turn	-on is do	minated by L <sub>S</sub> and L <sub>D</sub> )			

#### Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- b. Pulse width  $\leq 300~\mu s;~duty~cycle \leq 2~\%$



### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

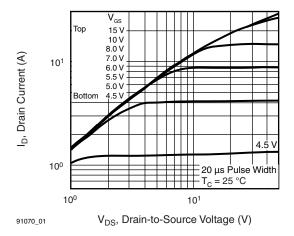


Fig. 1 - Typical Output Characteristics, T<sub>C</sub> = 25 °C

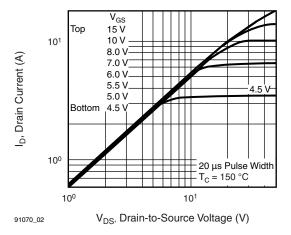


Fig. 2 - Typical Output Characteristics,  $T_C = 150 \, ^{\circ}\text{C}$ 

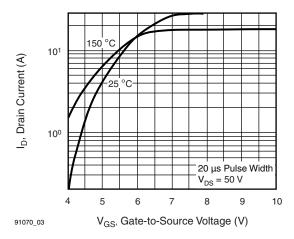


Fig. 3 - Typical Transfer Characteristics

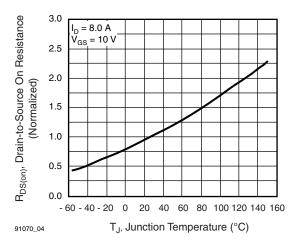


Fig. 4 - Normalized On-Resistance vs. Temperature

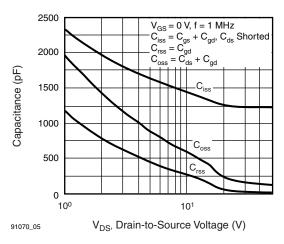


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

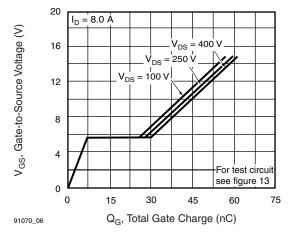


Fig. 6 - Typical Gate Charge vs. Drain-to-Source Voltage

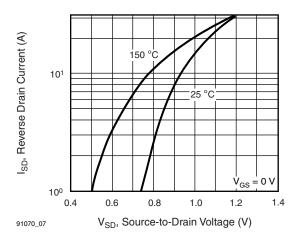


Fig. 7 - Typical Source-Drain Diode Forward Voltage

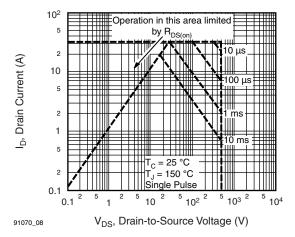


Fig. 8 - Maximum Safe Operating Area

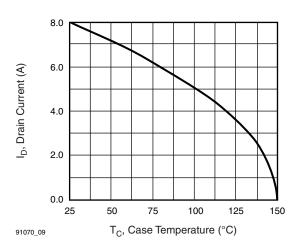


Fig. 9 - Maximum Drain Current vs. Case Temperature

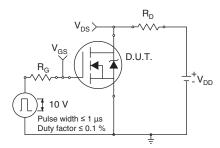


Fig. 10a - Switching Time Test Circuit

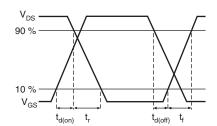


Fig. 10b - Switching Time Waveforms

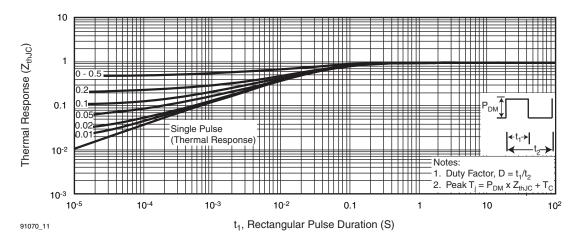


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case



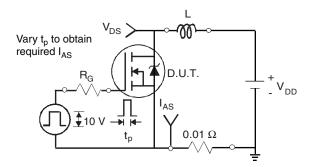


Fig. 12a - Unclamped Inductive Test Circuit

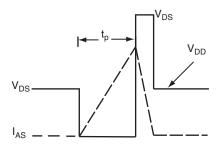


Fig. 12b - Unclamped Inductive Waveforms

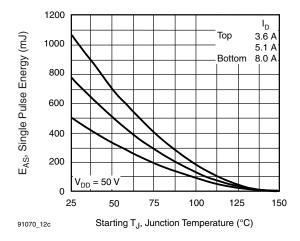


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

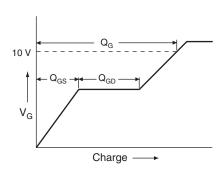


Fig. 13a - Basic Gate Charge Waveform

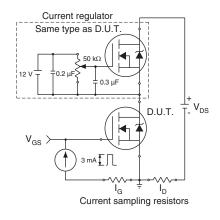
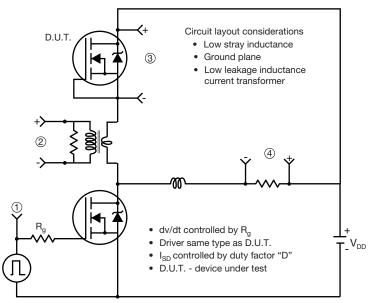


Fig. 13b - Gate Charge Test Circuit



#### Peak Diode Recovery dv/dt Test Circuit



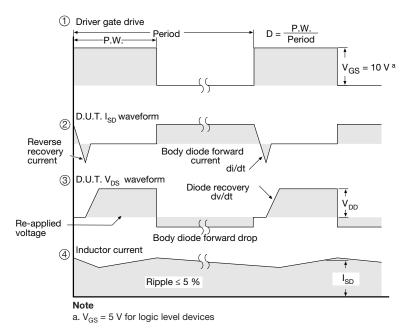


Fig. 14 - For N-Channel

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